600V Half Bridge Driver

PRODUCT SUMMARY

- **V_{OFFSET}** 600 V max.
- **I_O+/- (min)** 130 mA/270 mA
- **V_{OUT}** 10 V - 20 V
- **$t_{on/off}$ (typ.)** 160 ns/220 ns
- **Delay Matching** 30 ns

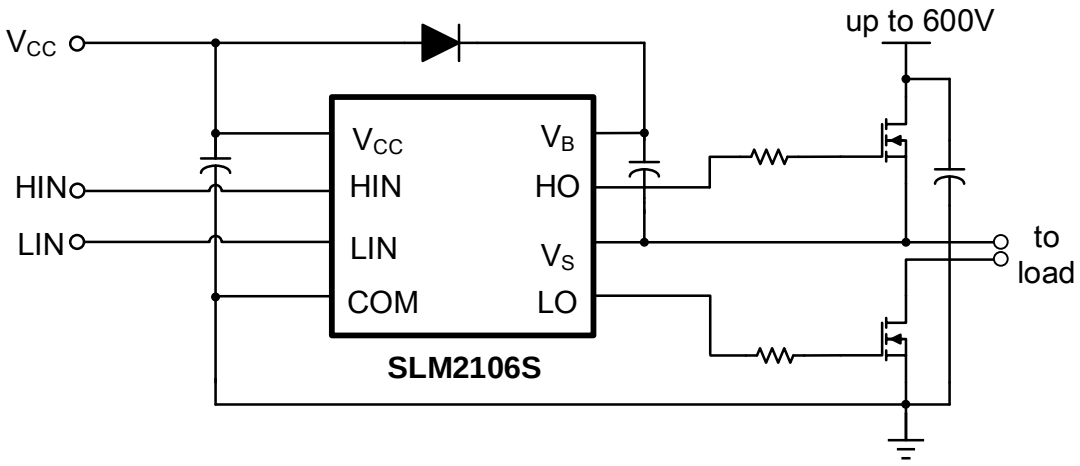
FEATURES

- Floating channel designed for bootstrap operation
- Fully operational to +600 V
- Tolerant to negative transient voltage, dV/dt immune
- Gate drive supply range from 10 V to 20 V
- Undervoltage lockout
- 3.3 V, 5 V, and 15 V logic compatible
- Cross-conduction prevention logic
- Matched propagation delay for both channels
- Outputs in phase with inputs
- RoHS compliant
- SOP8 and SOP14 package

GENERAL DESCRIPTION

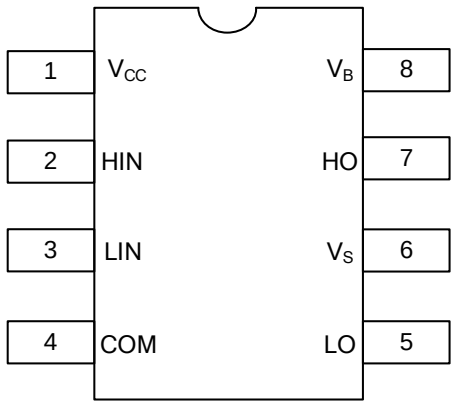
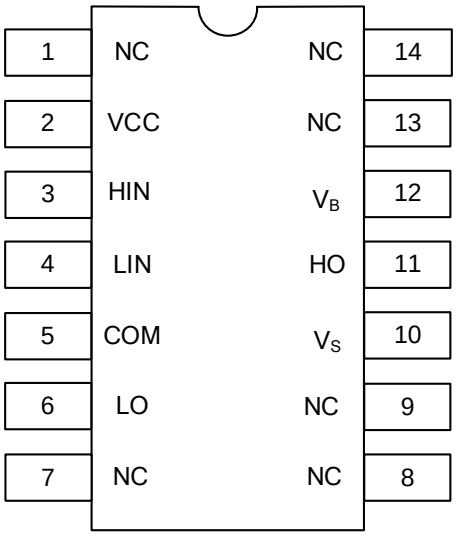
The SLM2106S is a high voltage, high speed power MOSFET and IGBT drivers. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. The logic input is compatible with standard CMOS or LSTTL output, down to 3.3 V logic. The output drivers feature a high pulse current buffer stage designed for minimum driver cross conduction. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high-side configuration which operates up to 600 V.

TYPICAL APPLICATION CIRCUIT



Refer to Lead Assignments for correct configuration. This diagram shows electrical connections only.

PIN CONFIGURATION

Package	SOP8	SOP14
Pin Configuration (Top View)		

PIN DESCRIPTION

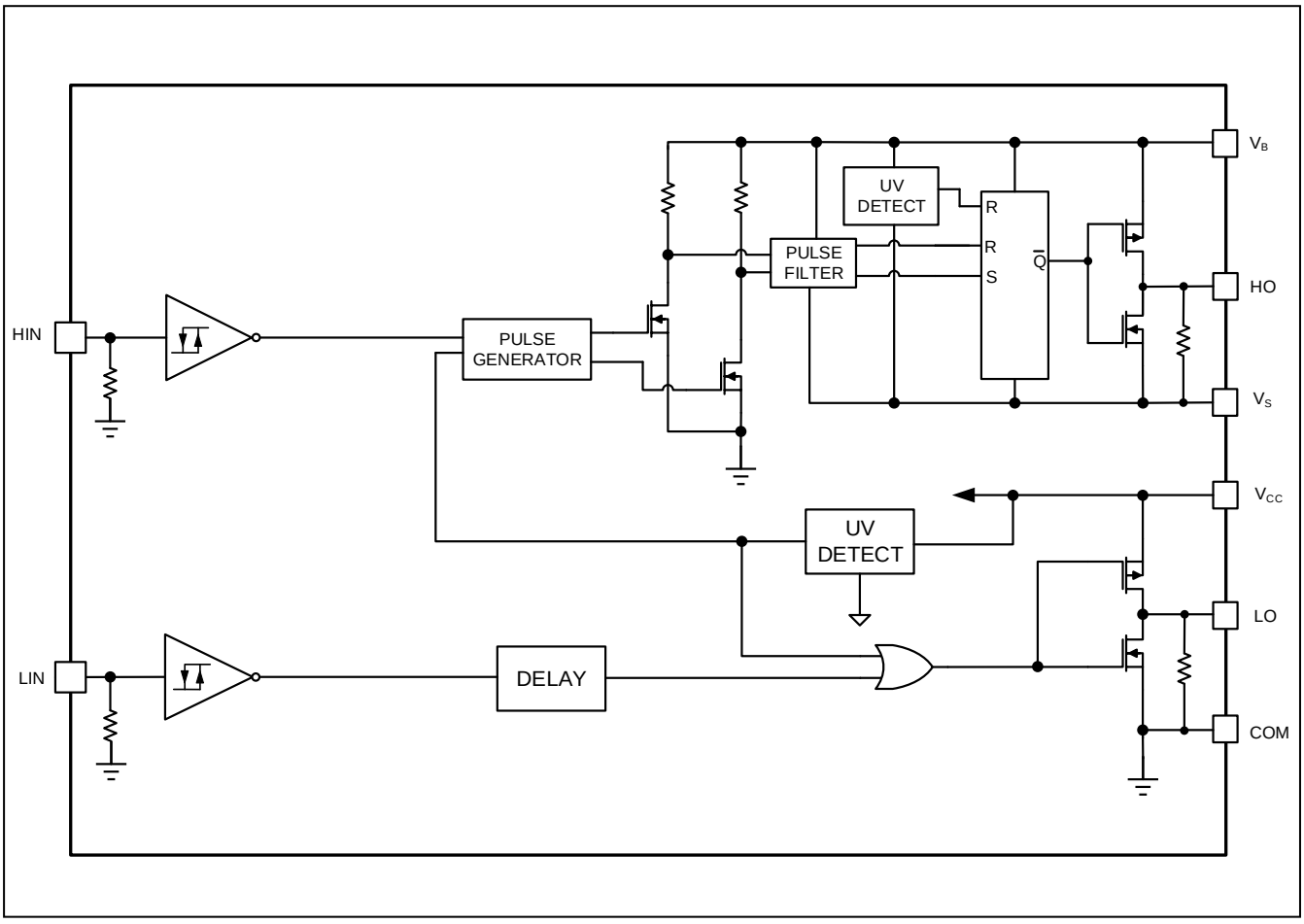
Pin No.		Pin Name	Description
SOP8	SOP14		
1	2	V_{CC}	Low-side and logic fixed supply
2	3	HIN	Logic input for high-side gate driver output (HO), in phase
3	4	LIN	Logic input for low-side gate driver output (LO), in phase
4	5	COM	Low-side return
5	6	LO	Low-side gate drive output
6	10	V_S	High-side floating supply return
7	11	HO	High-side gate drive output
8	12	V_B	High-side floating supply
	1,7,8,9,13 ,14	NC	Not connected

ORDERING INFORMATION

Industrial Range: -40°C to +125°C

Order Part No.	Package	QTY
SLM2106SCA-13GTR	SOP8, Pb-Free	2500/Reel
SLM2106SCJ-13GTR	SOP14,Pb-Free	4000/Reel

FUNCTIONAL BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Definition	Min.	Max.	Units
V_B	High-side floating absolute voltage	-0.3	625	V
V_S	High-side floating supply offset voltage	V_B - 25	V_B + 0.3	
V_{HO}	High-side floating output voltage	V_S - 0.3	V_B + 0.3	
V_{CC}	Low-side and logic fixed supply voltage	-0.3	25	
V_{LO}	Low-side output voltage	-0.3	V_{CC} + 0.3	
V_{IN}	Logic input voltage (HIN & LIN)	-0.3	V_{CC} + 0.3	
dV_S/dt	Allowable offset supply voltage transient	---	50	V/ns
P_D	Package power dissipation @ $T_A \leqslant +25°C$	---	0.625	W
θ_{JA}	Thermal resistance, junction to ambient	---	200	°C/W
T_J	Junction temperature	---	150	°C
T_S	Storage temperature	-55	150	
T_L	Lead temperature (soldering, 10 seconds)	---	300	

Note: Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

RECOMMENDED OPERATION CONDITIONS

Symbol	Definition	Min.	Max.	Units
V_B	High-side floating absolute voltage	V_S + 10	V_S + 20	V
V_S	High-side floating supply offset voltage		600	
V_{HO}	High-side floating output voltage	V_S	V_B	
V_{CC}	Low-side and logic fixed supply voltage	10	20	
V_{LO}	Low-side output voltage	0	V_{CC}	
V_{IN}	Logic input voltage (HIN & LIN)	0	V_{CC}	
T_A	Ambient temperature	- 40	125	°C

Note: The input/output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions. The V_S offset rating is tested with all supplies biased at a 15 V differential.

DYNAMIC ELECTRICAL CHARACTERISTICS

V_{BIAS} (V_{CC}, V_{BS}) = 15 V, C_L = 1000 pF and T_A = 25°C unless otherwise specified.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
t_{on}	Turn-on propagation delay	V_S = 0 V	---	160	220	ns
t_{off}	Turn-off propagation delay	V_S = 0 V	---	220	280	
t_r	Turn-on rise time		---	70	170	
t_f	Turn-off fall time		---	35	90	
MT	Delay matching, HS & LS turn-on/off		---	---	30	

STATIC ELECTRICAL CHARACTERISTICS

V_{BIAS} (V_{CC}, V_{BS}) = 15 V and T_A = 25°C unless otherwise specified. The V_{IN}, V_{TH}, and I_{IN} parameters are referenced to COM and are applicable to all logic input leads: HIN and LIN. The V_O and I_O parameters are referenced to COM and are applicable to the respective output leads: HO or LO.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{IH}	Logic “1” input voltage	V_{CC} = 10 V to 20V	2.5	---	---	V
V_{IL}	Logic “0” input voltage		---	---	0.8	
V_{OH}	High level output voltage, V_{BIAS} - V_O	I_O = 2 mA	---	0.05	0.2	
V_{OL}	Low level output voltage, V_O		---	0.02	0.1	
I_{LK}	Offset supply leakage current	V_B = V_S = 600 V	---	---	50	µA
I_{QBS}	Quiescent V_{BS} supply current	V_{IN} = 0 V	---	60	78	
I_{QCC}	Quiescent V_{CC} supply current		---	220	280	
I_{IN+}	Logic “1” input bias current	V_{IN} = 5V	---	8	15	
I_{IN-}	Logic “0” input bias current	V_{IN} = 0V	---	---	5	
V_{CCUV+} V_{BSUV+}	V_{CC} & V_{BS} supply undervoltage positive going threshold		8	8.9	9.8	V
V_{CCUV-} V_{BSUV-}	V_{CC} & V_{BS} supply undervoltage negative going threshold		7.4	8.2	9	
I_{O+}	Output high short circuit pulsed current	V_O = 15 V, V_{IN} = Logic “1”, PW ⩽ 10 µs	130	290		mA
I_{O-}	Output low short circuit pulsed current	V_O = 0 V, V_{IN} = Logic “0”, PW ⩽ 10 µs	270	600		

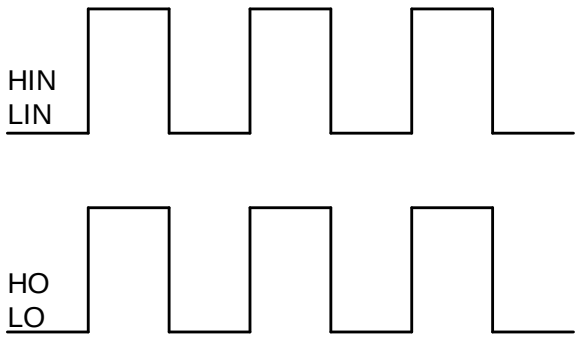


Figure 1. Input/Output Timing Diagram

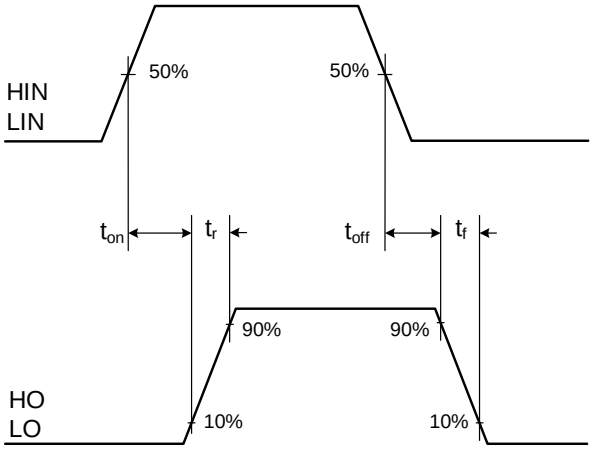


Figure 2. Switching Time Waveform

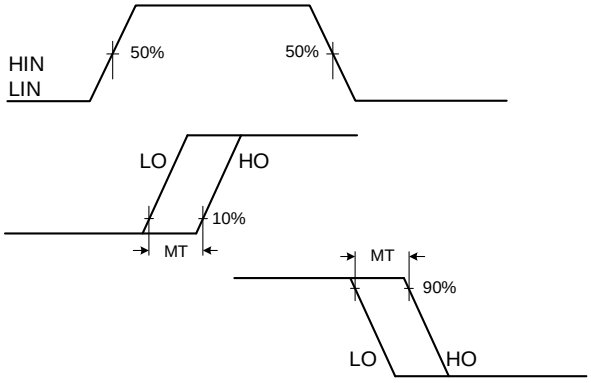
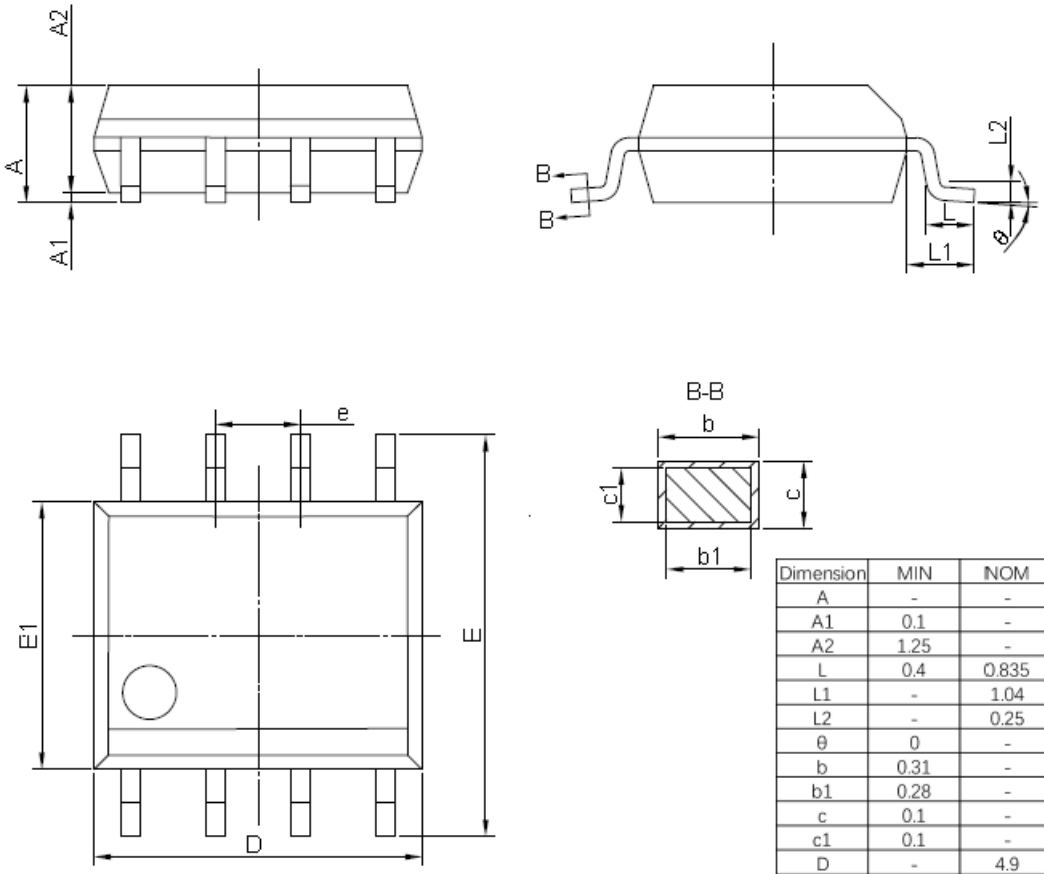


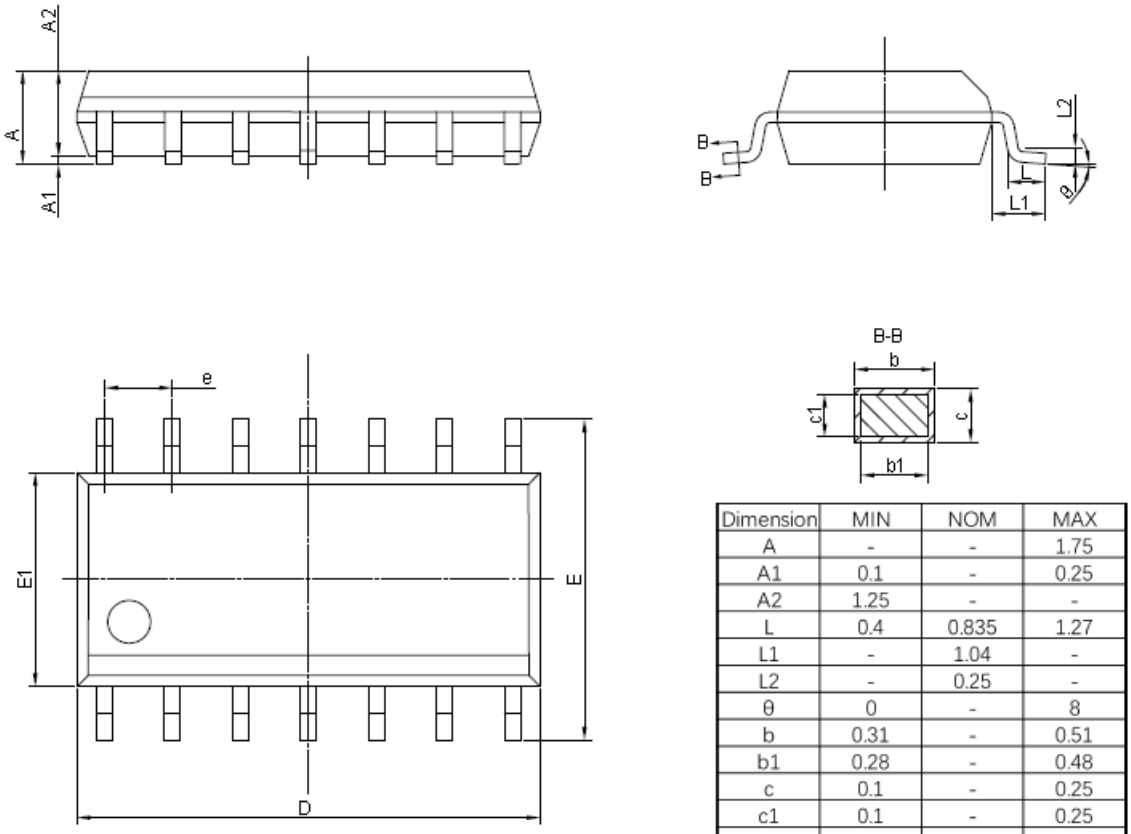
Figure 3. Delay Matching Waveform

PACKAGE CASE OUTLINES



Dimension	MIN	NOM	MAX
A	-	-	1.75
A1	0.1	-	0.25
A2	1.25	-	-
L	0.4	0.835	1.27
L1	-	1.04	-
L2	-	0.25	-
θ	0	-	8
b	0.31	-	0.51
b1	0.28	-	0.48
c	0.1	-	0.25
c1	0.1	-	0.25
D	-	4.9	-
E	-	6	-
E1	-	3.9	-
e	1.27 BSC		
Unit : mm			

Figure 4. SOP8 Outline Dimensions



Dimension	MIN	NOM	MAX
A	-	-	1.75
A1	0.1	-	0.25
A2	1.25	-	-
L	0.4	0.835	1.27
L1	-	1.04	-
L2	-	0.25	-
θ	0	-	8
b	0.31	-	0.51
b1	0.28	-	0.48
c	0.1	-	0.25
c1	0.1	-	0.25
D	-	8.65	-
E	-	6	-
E1	-	3.9	-
e	1.27 BSC		
Unit : mm			

Figure 5. SOP14 Outline Dimensions

REVISION HISTORY

Note: page numbers for previous revisions may differ from page numbers in current version

Page or Item	Subjects (major changes since previous revision)
Rev 1.0 datasheet, 2019-8-29	
Whole document	new company logo released
Page 1	Removed “Fig 1. ”
Rev 1.1 datasheet, 2019-10-21	
Page 1	Change “high side and low side driver” to “600V half-bridge driver”
Rev 1.2 datasheet, 2021-Oct-29	
Whole datasheet	Update the Logo and format
Page 1	Remove PDIP-8 package
Page 2	Remove SLM2106SCA-GT and SLM2106SDA-GT in ordering information
Page 3	Update the functional block diagram
Page 5	Update the V_{OH}, V_{OL} and I_{QCC} in static electrical characteristics table
Rev 1.3 datasheet, 2022-May-10	
Whole datasheet	Change package name from SOIC-8 to SOP8, SOIC-14 to SOP14, and update the package case outlines